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Product Change Notification 2011L0909
Wire bond change Gold to Copper

February 24th 2012

Dear Customer,

Our Rohm LSI Quality Assurance Division intend to replace the current bond wire material Gold with that of Copper.

Please kindly refer to the attached PCN and documentation.

According to our internal investigations the planned material modification will have no impact on form, fit, function, processing, and reliability of the affected products.

Performance of the modified and the current version will be same.

Please kindly check the PCN and the accompanying data and advise your approval for receiving the changed product in the future by completing the Reply Box at the bottom of the PCN2011L0909.

Should there be anything unclear requiring further explanations, please kindly let us know.

With kind regards,

Walter Götz
Rohm Semiconductor GmbH
Quality Assurance Manager

Geschäftsführer: Christian André, Masaki Sakai HRB 5700 Amtsgericht Krefeld

ROHM SEMICONDUCTOR

LSI Quality Assurance Div.,
LSI Manufacturing Headquarters,
ROHM Co., Ltd.

／産形浩司

Product Change Notice／変更申請書

Introduction of LSI products with Copper Wires／銅ワイヤー化

Change Notification #／発行 No: 2011L0909
Date of issue／発行日: 9th September, 2011
Applicable products／適用範囲: All IC products manufactured by ROHM／ﾛｰﾑ LSI 製品
Description of Change／変更内容: To use copper wires in LSI products instead of gold wires.
金ワイヤーから銅ワイヤーへ変更
Reason for Change／変更理由: To meet the market requirement／市場要求
Details of Change／変更詳細:

Component／使用材料	Conventional／従来	After the change／変更後
Molding Resin／ﾓｰﾙﾄﾞ	No change／変更無し	
Chip／ﾁｯﾌﾟ	No change／変更無し	
Lead frame／ﾘｰﾄﾞﾌﾚｰﾑ	No change／変更無し	
Die Bonding Material／ﾀﾞｲﾎﾞﾝﾃﾞｨﾝｸﾞ材	No change／変更無し	
Wire／ﾜｲﾔｰ	Gold／金	Copper／銅
BGA PWB／BGA 基板	No change／変更無し	

Mechanical and Electrical characteristics before and after 変更前後の特性／:

	Conventional／従来	After the change／変更後
Molding Method／樹脂封止方法	No change／変更無し	
Electrical Characteristics／電気特性	No change／変更無し	
Reliability／信頼性	No change／変更無し	
Recommended Mounting(Jisso) Conditions／実装条件	No change／変更無し	

Time of implementation／変更時期: From December, 2011（After an approval／ご承認後）

Reply to Process Change Request／回答
Answer（1：Approved／承認　2：Approved with exception／条件付承認　3：Rejected／却下）

Approval Exception/Reason for Rejected／条件または却下理由

Date　／　／　　Issue：＿＿＿＿＿＿　　Approval：＿＿＿＿＿＿